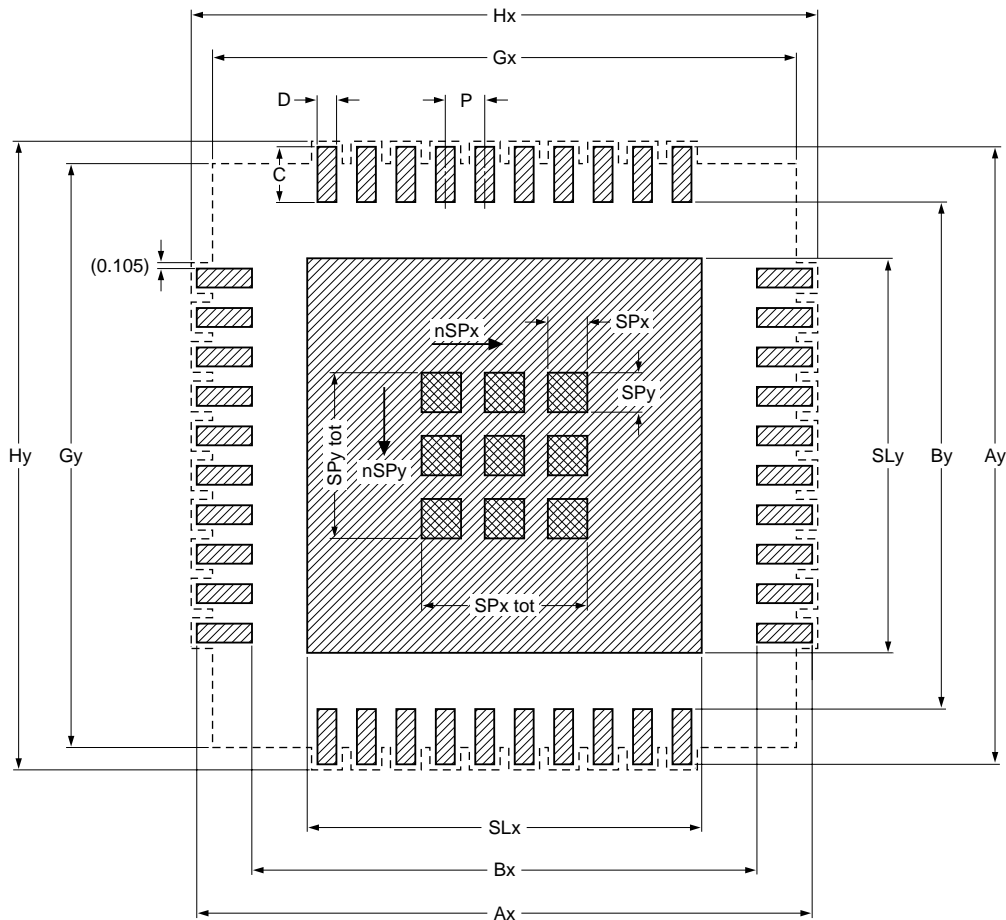





Footprint information for reflow soldering of HVQFN16 package

SOT758-3



Generic footprint pattern

Refer to the package outline drawing for actual layout

-  solder land
-  solder paste deposit
-  solder land plus solder paste
- occupied area

nSPx	nSPy
1	1

DIMENSIONS in mm

P	Ax	Ay	Bx	By	C	D	SLx	SLy	SPx tot	SPy tot	SPx	SPy	Gx	Gy	Hx	Hy
0.500	4.000	4.000	2.200	2.200	0.900	0.240	1.500	1.500	0.700	0.700	0.700	0.700	3.300	3.300	4.250	4.250